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With Glass Fiber Thermal Pad

This is a thermal conductive material coated with a conductive polymer polymer on a single layer of glass fiber net. Even on rough and uneven surfaces, it can achieve a good thermal conductive filling effect.



Features and Benefits

- 1.2 W/m.K
- High adhesion, low hardness
- The surface adhesion of the glass fiber is relatively weak, facilitating installation
- High electrical insulation
- High conformability, low hardness

Typical Applications

- Between the motherboard and the case
- AC/DC power supply
- Uninterruptible Power Supply (UPS)
- Vehicle-mounted equipment, charger
- Thermal components for transmission control

Typical Properties		
Attribute	Value	Test Method
	TP 120	-
Composition	Ceramic Filler + Silicone	-
Color	Blue	Visual
Thickness (mm)	0.3 to 15.0	ASTM D374
Density (g/cc)	2.07	ASTM D792
Hardness (Shore OO)	30±5	GB/T531
Usage Temperature (°C)	- 40 to 150	-
Electrical		
Breakdown Voltage (kV/mm)	≥ 10	ASTM D149
Volume Resistivity (Ω.cm)	1×10^{13}	ASTM D257
Dielectric Constant	5.41	ASTM D150
Flammability	V-0	UL 94
Thermal		
Thermal Conductivity (W/m.K)	1.2	ISO 22007-2